

In the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Cancelled)

2. (Currently Amended) An apparatus to control slurry flow in a chemical mechanical polishing apparatus for planarizing an object to be polished by supplying slurry on a grinding pad through a slurry injection nozzle, the apparatus comprising:

a slurry supply unit to supply slurry to the slurry injection nozzle through a slurry supply line; a by-pass diverged from the slurry supply line;

a photo image sensor to detect a generally cross-sectional image of the slurry flowing in the by-pass diverged from the slurry supply line;

a slurry measuring unit to analyze the image captured by the photo image sensor to measure the sizes of particles included in the slurry and the density of the slurry;

a diluent solution supply unit to supply diluent solution into the by-pass to reduce a concentration of particles in the slurry; and

a slurry flow control unit to control the slurry supply unit based upon the particle sizes and the slurry density measured by the slurry measuring unit.

3. (Currently Amended) An apparatus as defined in claim 2, wherein the diluent solution is pure water or a solution with the same composition-ingredient as the slurry solution.

4. (Cancelled)

5. (Previously Presented) A method to control slurry flow in a chemical mechanical polishing apparatus for planarizing an object to be polished by supplying slurry on a grinding pad through a slurry injection nozzle, the method comprising:

supplying slurry to the slurry injection nozzle through a slurry supply line;

introducing slurry into a by-pass diverged from the slurry supply line;

supplying a diluent solution into the by-pass to reduce a concentration of particles of the

slurry;

capturing a cross-sectional image of the by-pass to measure the sizes of particles included in the slurry and the density of the slurry; and

controlling supply of the slurry based upon the measured sizes of particles and density of slurry.

6. (Currently Amended) A method as defined in claim 5, wherein the diluent solution is pure water or a solution with the same composition-ingredient as the slurry solution.

7. (Currently Amended) A method as defined in claim 5, wherein the density of the slurry supplied to the slurry injection nozzle is calculated to be higher than a density of in proportion to an amount of the supplied diluent solution.

8. (Currently Amended) A method as defined in claim 5, wherein an amount of the particles of the slurry supplied to the slurry injection nozzle is calculated to be higher in proportion to than an amount of particles of the supplied diluent solution.

9. (Currently Amended) A method as defined in claim 5, wherein the density of the slurry in the slurry supply line is calculated to be higher in inverse proportion to the amount of supplied slurry.

10. (Currently Amended) A method as defined in claim 5, wherein an amount of the particles in the slurry supply line is calculated to be higher in inverse proportion to the amount of supplied slurry.